

IN THE CLAIMS

Please amend the claims to read as follows:

Listing of Claims

1-10. (Canceled).

11. (New) A resin molded type semiconductor device comprising: a semiconductor chip which is mounted on a die pad of a lead frame; thin metal wires which electrically connect terminals of an upper face of said semiconductor chip to inner lead portions of said lead frame; a sealing resin which seals an outer peripheral region of said semiconductor chip, said region including a thin metal wire region of the upper face of said semiconductor chip; and outer lead portions which are arranged in a bottom face region of said sealing resin and which are formed to be continuous to respective inner lead portions, wherein at least one groove portion is formed in a surface of each of said inner lead portions, a connecting portion of each of said thin metal wires is coupled to a respective inner lead portion at a flat surface region of said respective inner lead portion adjacent said at least one groove portion.

12. (New) A resin molded type semiconductor device according to claim 11, wherein exposed faces of said outer lead portion are arranged in a same level as an outer face of said sealing resin.

13. (New) A resin molded type semiconductor device comprising:

a semiconductor chip which is mounted on a die pad of a lead frame;

thin metal wires which electrically connect terminals of an upper face of said semiconductor chip to inner lead portions of said lead frame;

a sealing resin which seals an outer peripheral region of said semiconductor chip and which contacts a bottom face of said semiconductor chip, said region including a thin metal wire region of the upper face of said semiconductor chip; and

outer lead portions which are arranged in a bottom face region of said sealing resin and which are formed to be continuous to respective inner lead portions.